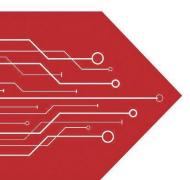
MSKSEMI















ESD

TVS

TSS

MOV

GDT

PLED

Product data sheet

www.msksemi.com

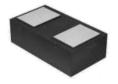
DFN1006

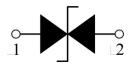
Features . Pin Description Schematic Diagram

■ Low Capacitance: 8pF(typ.)

■ Reverse Working Voltage: 12V

■ IEC 61000-4-2 (ESD Air): ±30KV IEC 61000-4-2 (ESD Contact): ±30KV IEC 61000-4-5 (Lightning 8/20µs): 8A





Applications

■ Smart Phone and Tablet PC

- TV and Set Top Box
- Wearable Devices
- PDA

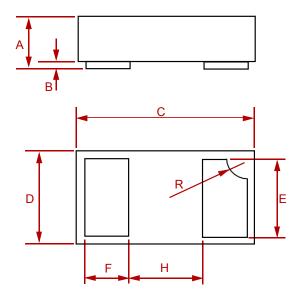
Limiting Values($T_A = 25$ °C, unless otherwise specified)

Symbol	Parameter	Conditions		Max	Unit
V _{ESD}	Electrostatic Discharge Voltage	IEC 61000-4-2; Contact Discharge	-	±30	kV
		IEC 61000-4-2; Air Discharge	-	±30	kV
P _{PP}	Peak Pulse Power	t _P = 8/20 μs	-	150	W
I _{PPM}	Rated Peak Pulse Current	t _P = 8/20 μs	-	8.0	Α
T _A	Ambient Temperature Range	-	-55	125	$^{\circ}\!\mathbb{C}$
T _{stg}	Storage Temperature Range	-	-55	150	$^{\circ}\!\mathbb{C}$

Electrical Characteristics(T_A = 25 °C, unless otherwise specified)

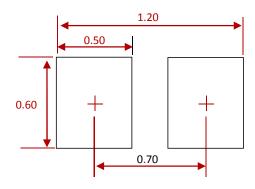
Symbol	Parameter	Conditions	Min	Тур.	Max	Unit
V _{RWM}	Reverse Working Voltage	T _A = 25 °C	-	-	12.0	V
V _{BR}	Breakdown Voltage	I _R = 1mA; T _A = 25 °C	14.0	14.5	15.0	V
I _R	Reverse Leakage Current	V _{RWM} = 12V; T _A = 25 °C	-	-	0.1	μΑ
Vc	Clamping Voltage	I _{PP} =8.0A, t _P =8/20μs	-	-	19.0	V
Сл	Junction Capacitance	V _R = 0V, f = 1 MHz	-	8.0	8.5	pF

PACKAGE MECHANICAL DATA



Direc	Inches		Millimeters		
Dim	MIN	MAX	MIN	MAX	
Α	0.0125	0.02	0.32	0.52	
В	0.000	0.002	0.00	0.05	
С	0.037	0.043	0.95	1.080	
D	0.022	0.027	0.55	0.680	
E	0.016	0.024	0.40	0.60	
F	0.008	0.012	0.20	0.30	
Н	0.015Typ.		0.40Typ.		
R	0.001	0.005	0.05	0.15	

Suggested Pad Layout



NOTES:

- 1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
- 2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

REEL SPECIFICATION

P/N	PKG	QTY
ESD12VV1BL-MS	DFN1006	10000



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